## DECLARATION AND POWER OF ATTORNEY

As a below named inventor, I hereby declare that.

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

## WAFER SPACE SUPPORTING APPARATUS INSTALLED ON ELECTROSTATIC CHUCK AND METHOD FOR FABRICATING SAME

the specification of which is attached hereto unless the following box is checked: \_ as United States Application Number or PCT International Application Number and was amended on \_ \_\_\_\_\_ (if applicable). I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above. I acknowledge the duty to disclose information which is known by me to be material to patentability as defined in Title 37, Code of Federal Regulations § 1.56. I hereby claim foreign priority benefits under Title 35, United States Code, § 119(a)-(d) or § 365(b) of any foreign application(s) for patent or inventor's certificate, or § 365(a) of any PCT International application which designated at least one country other than the United States, listed below and have also identified below any foreign application for patent or inventor's certificate, or PCT International application having a filing date before that of the application on which priority is claimed: PRIOR FOREIGN APPLICATION(S) **PRIORITY** COUNTRY DAY/MONTH/YEAR FILED NUMBER CLAIMED 29/May/2001 Yes 2001-29656 Republic of Korea I hereby claim the benefit under Title 35, United States Code § 119(e) of any United States provisional application(s) listed below. APPLICATION NO. FILING DATE

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s), or § 365(c) of any PCT International application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose information which is known by me to be material to patentability as defined in Title 37, Code of Federal Regulations § 1.56 which became available between the filing date of the prior application and the national or PCT International filing date of this application.

Post Office Address
Same as above

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Docket No.\_242/11.5

APPLICATION SERIAL NO.	FILING DAT	E	STATUS: PATENTED, ABANDONE	
Address all correspondence to Eugene M. Lee, The Law Offices of Eugene M. Lee, PLLC, 2111 Wilson Boulevard, Suite 1200, Arlington, Virginia 22201. Address all telephone communications to Eugene M. Lee at (703) 525-0978.  Thereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine of imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.  Signature of First or Sole Inventor  Date				
Sun-Young LEE		Lee. Si	21/1/2	11/14/202
Residence Address #8-202, Samsung Apt., Maetan 2-dong, Paldal-gu, Suwon-city, Kyonggi-do, Republic of Korea			Country of Citizenship Republic of Korea	

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent application of

Sun-Young LEE

Group Art Unit: (Unassigned)

Serial No. (Unassigned)

Examiner: (Unassigned)

Filed: Concurrently

For: WAFER SPACE SUPPORTING APPARATUS INSTALLED ON ELECTROSTATIC CHUCK AND METHOD FOR FABRICATING THE SAME

## **NOTICE OF CHANGE OF ADDRESS**

Assistant Commissioner for Patents Washington, D.C. 20231

Sir:

All future correspondence in connection with the subject patent should be sent to the address listed below:

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Respectfully submitted,

January 14, 2002 Date

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